Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

Contact us

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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

Kingbright

101.2mm (4.0INCH) SINGLE DIGIT NUMERIC DISPLAY

Part Number: SA40-18EWA High Efficiency Red

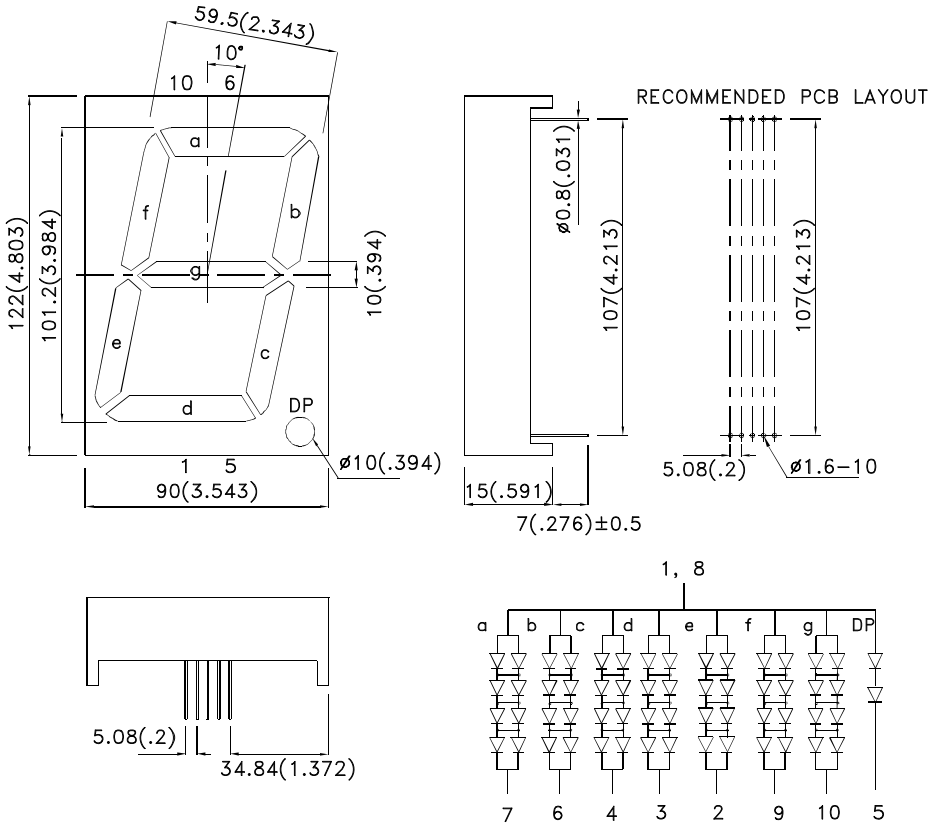
Features

- Large size.
- 4.0 inch digit height.
- Low current operation.
- Excellent character appearance.
- High light output.
- Easy mounting on P.C. boards or sockets.
- Mechanically rugged.
- Standard : gray face, white segment..
- RoHS compliant.

Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

Package Dimensions& Internal Circuit Diagram



Notes:
1. All dimensions are in millimeters (inches), Tolerance is ±0.25(0.01")unless otherwise noted.
2. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

Selection Guide

Part No.	Dice	Lens Type	Iv (ucd) [1] @ 10mA		Description
			Min.	Typ.	
SA40-18EWA	High Efficiency Red (GaAsP/GaP)	White Diffused	14000	23000	Common Anode, Rt. Hand Decimal.

Note:
1. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

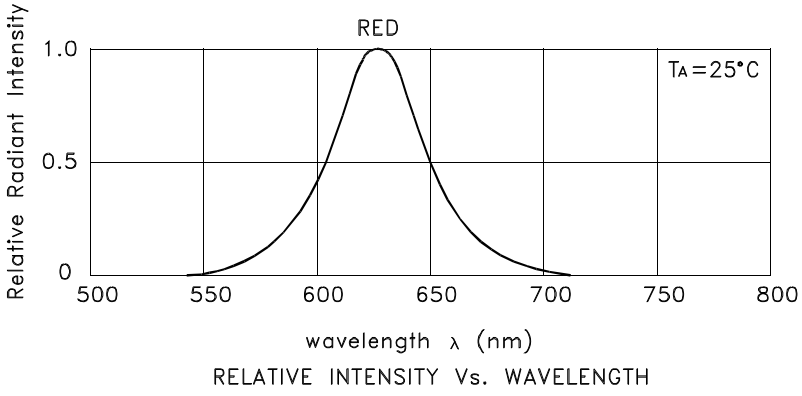
Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	High Efficiency Red	627		nm	I_F=20mA
λD [1]	Dominant Wavelength	High Efficiency Red	625		nm	I_F=20mA
Δλ1/2	Spectral Line Half-width	High Efficiency Red	45		nm	I_F=20mA
C	Capacitance	High Efficiency Red	15		pF	V_F=0V;f=1MHz
V_F [2]	Forward Voltage Per Segment Or (DP)	High Efficiency Red	8.0 (4.0)	10.0 (5.0)	V	I_F=20mA
I_R	Reverse Current Per Segment Or (DP)	High Efficiency Red		20 (10)	uA	V_R=5V (V_R=5V)

Notes:
1.Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

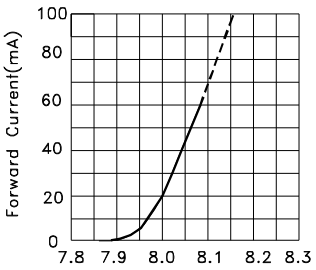
Parameter	High Efficiency Red	Units
Power dissipation Per Segment Or (DP)	600 (150)	mW
DC Forward Current Per Segment Or (DP)	60 (30)	mA
Peak Forward Current [1] Per Segment Or (DP)	320 (160)	mA
Reverse Voltage Per Segment Or (DP)	5 (5)	V
Operating / Storage Temperature	-40°C To +85°C	
Lead Solder Temperature[2]	260°C For 3-5 Seconds	

Notes:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. 2mm below package base.

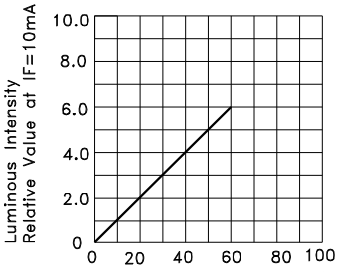


RELATIVE INTENSITY Vs. WAVELENGTH

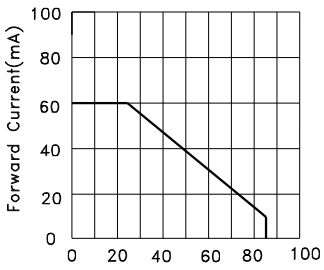
High Efficiency Red **SA40-18EWA**



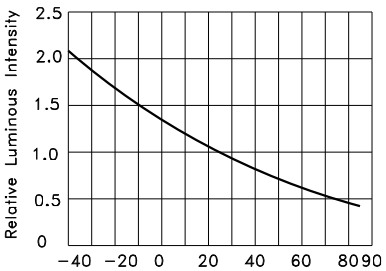
FORWARD CURRENT Vs
FORWARD VOLTAGE



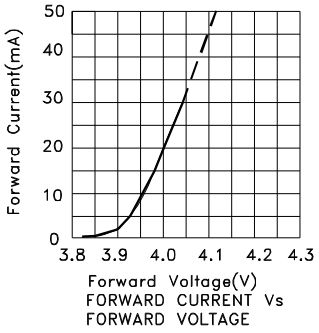
LUMINOUS INTENSITY Vs.
FORWARD CURRENT



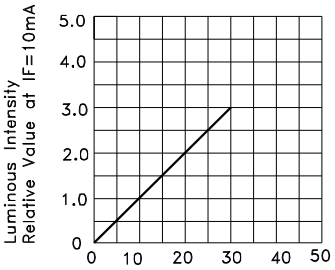
FORWARD CURRENT
DERATING CURVE



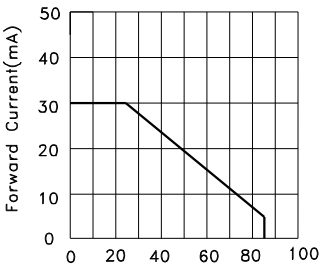
LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE



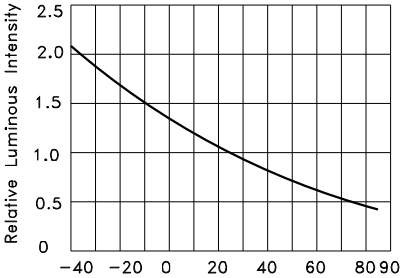
FORWARD CURRENT Vs
FORWARD VOLTAGE



LUMINOUS INTENSITY Vs.
FORWARD CURRENT

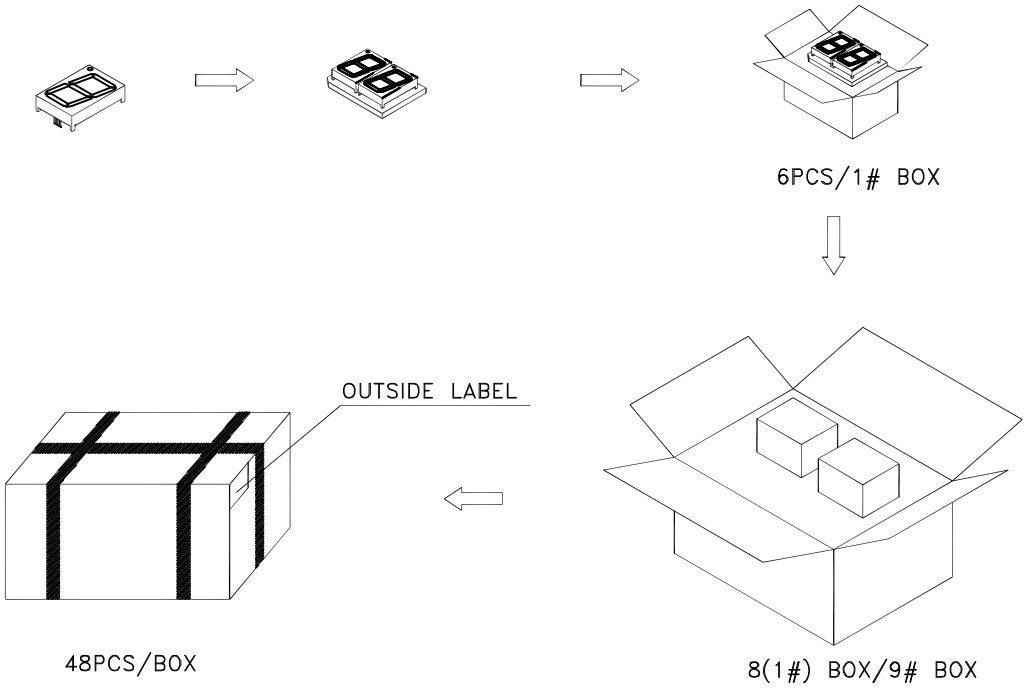


FORWARD CURRENT
DERATING CURVE

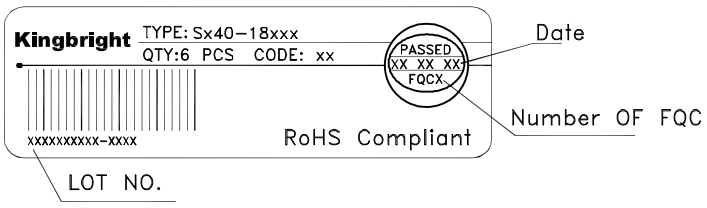


LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE

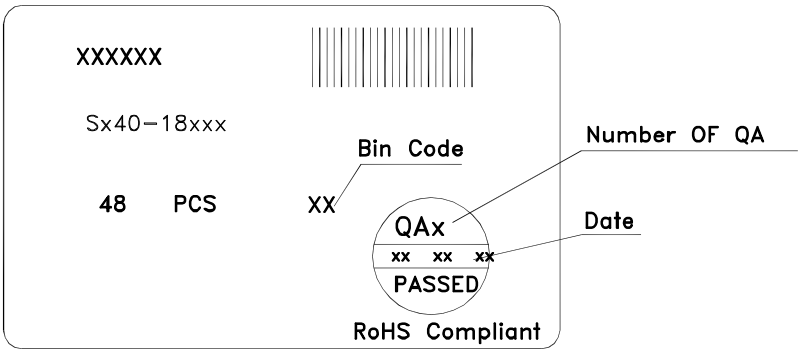
PACKING & LABEL SPECIFICATIONS **SA40-18EWA**



Inside Label on 1#BOX



Outside Label on Box

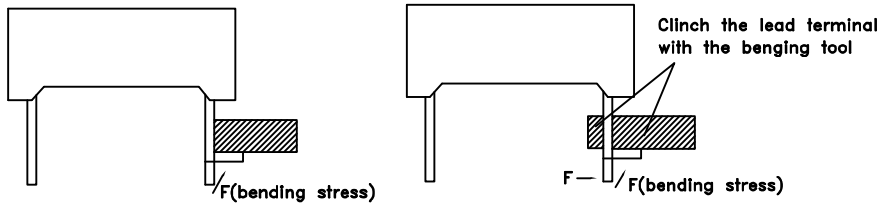


THROUGH HOLE DISPLAY MOUNTING METHOD

Lead Forming

Do not bend the component leads by hand without proper tools.

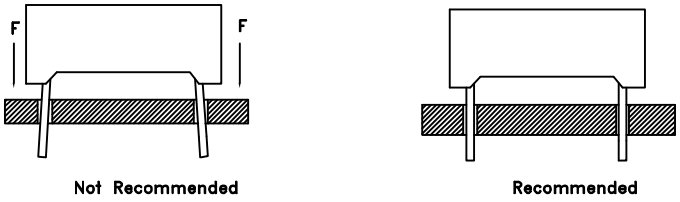
The leads should be bent by clinching the upper part of the lead firmly such that the bending force is not exerted on the plastic body.



Installation

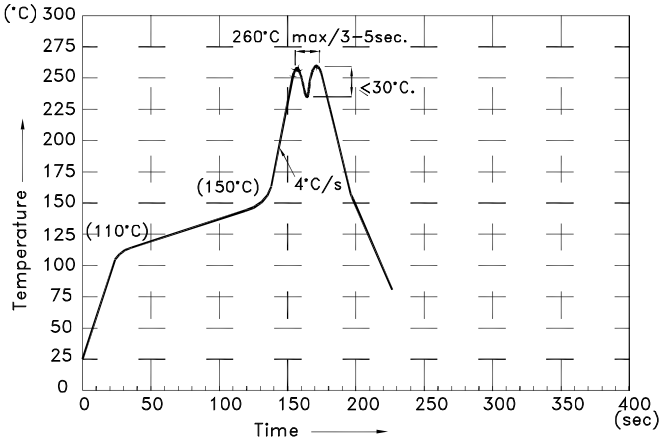
1.The installation process should not apply stress to the lead terminals.

2.When inserting for assembly, ensure the terminal pitch matches the substrate board's hole pitch to prevent spreading or pinching the lead terminals.



DISPLAY SOLDERING CONDITIONS

Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

1.Recommend the wave temperature 245°C~260°C.The maximum soldering temperature should be less than 260°C.

2.Do not apply stress on epoxy resins when temperature is over 85°C.

3.The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).

4.During wave soldering , the PCB top-surface temperature should be kept below 105°C

5.No more than once.

Soldering General Notes:

a. Through-hole displays are incompatible with reflow soldering.

b. If components will undergo multiple soldering processes, or other processes where the components may be subjected to intense heat, please check with Kingbright for compatibility.

CLEANING

1.Mild "no-clean" fluxes are recommended for use in soldering.

2. If cleaning is required, Kingbright recommends to wash components with water only. Do not use harsh organic solvents for cleaning, because they may damage the plastic parts .And the devices should not be washed for more than one minute.

CIRCUIT DESIGN NOTES

1.Protective current-limiting resistors may be necessary to operate the Displays.

2.LEDs mounted in parallel should each be placed in series with its own current-limiting resistor.